



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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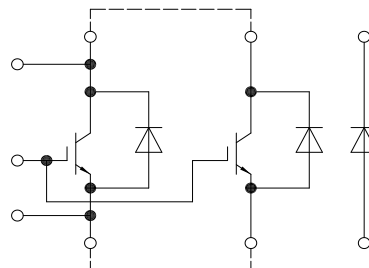
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



IHM-B Modul mit Chopper Konfiguration
IHM-B module with chopper configuration



$V_{CES} = 1700V$
 $I_{C\ nom} = 1600A / I_{CRM} = 3200A$

Typische Anwendungen

- Chopper-Anwendungen
- Hochleistungsumrichter
- Traktionsumrichter
- Windgeneratoren

Typical Applications

- Chopper applications
- High power converters
- Traction drives
- Wind turbines

Elektrische Eigenschaften

- Erweiterte Sperrschichttemperatur $T_{vj\ op}$
- Niedriges V_{CESat}

Electrical Features

- Extended operating temperature $T_{vj\ op}$
- Low V_{CESat}

Mechanische Eigenschaften

- 4 kV AC 1min Isolationsfestigkeit
- AlSiC Bodenplatte für erhöhte thermische Lastwechselfestigkeit
- Gehäuse mit CTI > 400
- Große Luft- und Kriechstrecken
- Hohe Last- und thermische Wechselfestigkeit
- Hohe Leistungsdichte
- IHM B Gehäuse

Mechanical Features

- 4 kV AC 1min insulation
- AlSiC base plate for increased thermal cycling capability
- Package with CTI > 400
- High creepage and clearance distances
- High power and thermal cycling capability
- High power density
- IHM B housing

Module Label Code

Barcode Code 128



DMX - Code



Content of the Code

Content of the Code	Digit
Module Serial Number	1 - 5
Module Material Number	6 - 11
Production Order Number	12 - 19
Datecode (Production Year)	20 - 21
Datecode (Production Week)	22 - 23

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IGBT-Chopper / IGBT-Chopper

Höchstzulässige Werte / Maximum Rated Values

Kollektor-Emitter-Sperrspannung Collector-emitter voltage	$T_{vj} = -40^{\circ}\text{C}$ $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	V_{CES}	1570 1700 1700	V
Kollektor-Dauergleichstrom Continuous DC collector current	$T_C = 100^{\circ}\text{C}, T_{vj\max} = 175^{\circ}\text{C}$	$I_{C\text{nom}}$	1600	A
Periodischer Kollektor-Spitzenstrom Repetitive peak collector current	$t_P = 1\text{ ms}$	I_{CRM}	3200	A
Gesamt-Verlustleistung Total power dissipation	$T_C = 25^{\circ}\text{C}, T_{vj\max} = 175^{\circ}\text{C}$	P_{tot}	10,5	kW
Gate-Emitter-Spitzenspannung Gate-emitter peak voltage		V_{GES}	+/-20	V

Charakteristische Werte / Characteristic Values

			min.	typ.	max.	
Kollektor-Emitter-Sättigungsspannung Collector-emitter saturation voltage	$I_C = 1600\text{ A}, V_{GE} = 15\text{ V}$ $I_C = 1600\text{ A}, V_{GE} = 15\text{ V}$ $I_C = 1600\text{ A}, V_{GE} = 15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$V_{CE\text{sat}}$	1,90 2,30 2,40	2,25	V V V
Gate-Schwellenspannung Gate threshold voltage	$I_C = 64,0\text{ mA}, V_{CE} = V_{GE}, T_{vj} = 25^{\circ}\text{C}$		V_{GEth}	5,20	5,80	6,40 V
Gateladung Gate charge	$V_{GE} = -15\text{ V} \dots +15\text{ V}$		Q_G	17,0		μC
Interner Gatewiderstand Internal gate resistor	$T_{vj} = 25^{\circ}\text{C}$		R_{Gint}	0,97		Ω
Eingangskapazität Input capacitance	$f = 1\text{ MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		C_{ies}	130		nF
Rückwirkungskapazität Reverse transfer capacitance	$f = 1\text{ MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		C_{res}	4,20		nF
Kollektor-Emitter-Reststrom Collector-emitter cut-off current	$V_{CE} = 1570\text{ V}, V_{GE} = 0\text{ V}, T_{vj} = 25^{\circ}\text{C}$		I_{CES}		5,0	mA
Gate-Emitter-Reststrom Gate-emitter leakage current	$V_{CE} = 0\text{ V}, V_{GE} = 20\text{ V}, T_{vj} = 25^{\circ}\text{C}$		I_{GES}		400	nA
Einschaltverzögerungszeit, induktive Last Turn-on delay time, inductive load	$I_C = 1600\text{ A}, V_{CE} = 900\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Gon} = 1,1\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	t_{don}	0,40 0,43 0,45		μs μs μs
Anstiegszeit, induktive Last Rise time, inductive load	$I_C = 1600\text{ A}, V_{CE} = 900\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Gon} = 1,1\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	t_r	0,18 0,20 0,20		μs μs μs
Abschaltverzögerungszeit, induktive Last Turn-off delay time, inductive load	$I_C = 1600\text{ A}, V_{CE} = 900\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Goff} = 0,6\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	t_{doff}	1,05 1,20 1,20		μs μs μs
Fallzeit, induktive Last Fall time, inductive load	$I_C = 1600\text{ A}, V_{CE} = 900\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Goff} = 0,6\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	t_f	0,30 0,46 0,51		μs μs μs
Einschaltverlustenergie pro Puls Turn-on energy loss per pulse	$I_C = 1600\text{ A}, V_{CE} = 900\text{ V}, L_S = 50\text{ nH}$ $V_{GE} = \pm 15\text{ V}$ $R_{Gon} = 1,1\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{on}	380 500 535		mJ mJ mJ
Abschaltverlustenergie pro Puls Turn-off energy loss per pulse	$I_C = 1600\text{ A}, V_{CE} = 900\text{ V}, L_S = 50\text{ nH}$ $V_{GE} = \pm 15\text{ V}$ $R_{Goff} = 0,6\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{off}	420 570 600		mJ mJ mJ
Kurzschlußverhalten SC data	$V_{GE} \leq 15\text{ V}, V_{CC} = 1000\text{ V}$ $V_{CE\max} = V_{CES} - L_{sCE} \cdot di/dt$ $t_P \leq 10\ \mu\text{s}, T_{vj} = 150^{\circ}\text{C}$		I_{SC}	7500		A
Wärmewiderstand, Chip bis Gehäuse Thermal resistance, junction to case	pro IGBT / per IGBT		R_{thJC}		11,6	K/kW
Wärmewiderstand, Gehäuse bis Kühlkörper Thermal resistance, case to heatsink	pro IGBT / per IGBT $\lambda_{\text{Paste}} = 1\text{ W}/(\text{m}\cdot\text{K})$ / $\lambda_{\text{grease}} = 1\text{ W}/(\text{m}\cdot\text{K})$		R_{thCH}	15,0		K/kW
Temperatur im Schaltbetrieb Temperature under switching conditions			$T_{vj\text{op}}$	-40	150	$^{\circ}\text{C}$

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Diode, Brems-Chopper / Diode, Brake-Chopper
Höchstzulässige Werte / Maximum Rated Values

Periodische Spitzensperrspannung Repetitive peak reverse voltage	$T_{vj} = -40^{\circ}\text{C}$ $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	V_{RRM}	1570 1700 1700	V
Dauergleichstrom Continuous DC forward current		I_F	1600	A
Periodischer Spitzenstrom Repetitive peak forward current	$t_P = 1 \text{ ms}$	I_{FRM}	3200	A
Grenzlastintegral I^2t - value	$V_R = 0 \text{ V}, t_P = 10 \text{ ms}, T_{vj} = 125^{\circ}\text{C}$ $V_R = 0 \text{ V}, t_P = 10 \text{ ms}, T_{vj} = 150^{\circ}\text{C}$	I^2t	630 595	kA ² s kA ² s
Spitzenverlustleistung Maximum power dissipation	$T_{vj} = 125^{\circ}\text{C}$	P_{RQM}	2400	kW
Mindesteinschaltdauer Minimum turn-on time		$t_{on \text{ min}}$	10,0	μs

Charakteristische Werte / Characteristic Values

			min.	typ.	max.	
Durchlassspannung Forward voltage	$I_F = 1600 \text{ A}, V_{GE} = 0 \text{ V}$ $I_F = 1600 \text{ A}, V_{GE} = 0 \text{ V}$ $I_F = 1600 \text{ A}, V_{GE} = 0 \text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	V_F	1,65 1,65 1,65	2,10	V V V
Rückstromspitze Peak reverse recovery current	$I_F = 1600 \text{ A}, -di_F/dt = 9000 \text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 900 \text{ V}$ $V_{GE} = -15 \text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	I_{RM}	1700 1950 2000		A A A
Sperrverzögerungsladung Recovered charge	$I_F = 1600 \text{ A}, -di_F/dt = 9000 \text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 900 \text{ V}$ $V_{GE} = -15 \text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	Q_r	450 740 840		μC μC μC
Abschaltenergie pro Puls Reverse recovery energy	$I_F = 1600 \text{ A}, -di_F/dt = 9000 \text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 900 \text{ V}$ $V_{GE} = -15 \text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{rec}	250 460 525		mJ mJ mJ
Wärmewiderstand, Chip bis Gehäuse Thermal resistance, junction to case	pro Diode / per diode		R_{thJC}		15,9	K/kW
Wärmewiderstand, Gehäuse bis Kühlkörper Thermal resistance, case to heatsink	pro Diode / per diode $\lambda_{\text{Paste}} = 1 \text{ W}/(\text{m}\cdot\text{K}) / \lambda_{\text{grease}} = 1 \text{ W}/(\text{m}\cdot\text{K})$		R_{thCH}	16,0		K/kW
Temperatur im Schaltbetrieb Temperature under switching conditions			$T_{vj \text{ op}}$	-40	150	$^{\circ}\text{C}$

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Diode, Revers / Diode, Reverse

Höchstzulässige Werte / Maximum Rated Values

Periodische Spitzensperrspannung Repetitive peak reverse voltage	$T_{vj} = -40^{\circ}\text{C}$ $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	V_{RRM}	1570 1700 1700	V
Dauergleichstrom Continuous DC forward current		I_F	1200	A
Periodischer Spitzenstrom Repetitive peak forward current	$t_P = 1 \text{ ms}$	I_{FRM}	2400	A
Grenzlastintegral I^2t - value	$V_R = 0 \text{ V}, t_P = 10 \text{ ms}, T_{vj} = 125^{\circ}\text{C}$ $V_R = 0 \text{ V}, t_P = 10 \text{ ms}, T_{vj} = 150^{\circ}\text{C}$	I^2t	140 130	kA^2s kA^2s
Spitzenverlustleistung Maximum power dissipation	$T_{vj} = 125^{\circ}\text{C}$	P_{RQM}	1200	kW
Mindesteinschaltdauer Minimum turn-on time		$t_{on \text{ min}}$	10,0	μs

Charakteristische Werte / Characteristic Values

			min.	typ.	max.	
Durchlassspannung Forward voltage	$I_F = 1200 \text{ A}, V_{GE} = 0 \text{ V}$ $I_F = 1200 \text{ A}, V_{GE} = 0 \text{ V}$ $I_F = 1200 \text{ A}, V_{GE} = 0 \text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	V_F	1,80 1,90 1,95	2,20	V V V
Rückstromspitze Peak reverse recovery current	$I_F = 1200 \text{ A}, -di_F/dt = 7700 \text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 900 \text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	I_{RM}	1250 1350 1400		A A A
Sperrverzögerungsladung Recovered charge	$I_F = 1200 \text{ A}, -di_F/dt = 7700 \text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 900 \text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	Q_r	280 460 510		μC μC μC
Abschaltenergie pro Puls Reverse recovery energy	$I_F = 1200 \text{ A}, -di_F/dt = 7700 \text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 900 \text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{rec}	180 300 345		mJ mJ mJ
Wärmewiderstand, Chip bis Gehäuse Thermal resistance, junction to case	pro Diode / per diode		R_{thJC}		31,9	K/kW
Wärmewiderstand, Gehäuse bis Kühlkörper Thermal resistance, case to heatsink	pro Diode / per diode $\lambda_{\text{Paste}} = 1 \text{ W}/(\text{m}\cdot\text{K}) / \lambda_{\text{grease}} = 1 \text{ W}/(\text{m}\cdot\text{K})$		R_{thCH}	32,5		K/kW
Temperatur im Schaltbetrieb Temperature under switching conditions			$T_{vj \text{ op}}$	-40	150	$^{\circ}\text{C}$

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Modul / Module

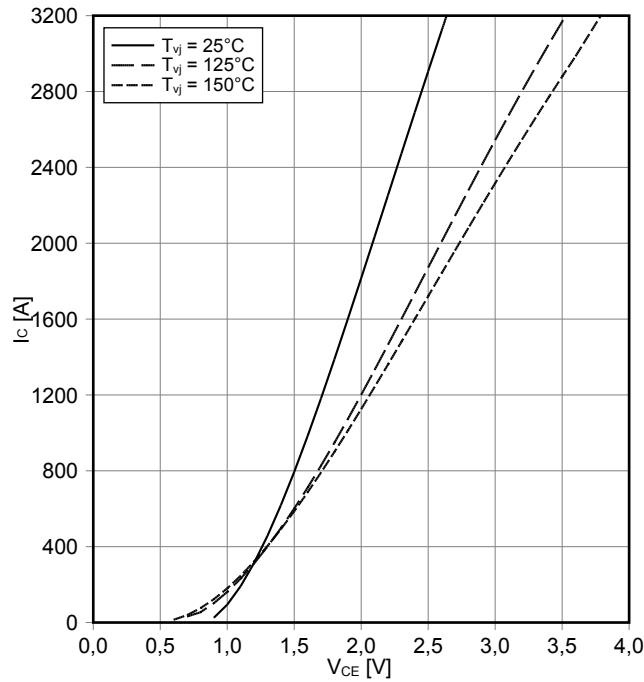
Isolations-Prüfspannung Isolation test voltage	RMS, f = 50 Hz, t = 1 min.	V _{ISOL}	4,0		kV
Material Modulgrundplatte Material of module baseplate			AlSiC		
Kriechstrecke Creepage distance	Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal		32,2 32,2		mm
Luftstrecke Clearance	Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal		19,1 19,1		mm
Vergleichszahl der Kriechwegbildung Comperative tracking index		CTI	> 400		
			min.	typ.	max.
Modulstreuintuktivität Stray inductance module		L _{SCE}		6,0	nH
Modulleitungswiderstand, Anschlüsse - Chip Module lead resistance, terminals - chip	T _c = 25°C, pro Schalter / per switch	R _{CC'+EE'} R _{AA'+CC'}		0,15 0,24	mΩ
Lagertemperatur Storage temperature		T _{stg}	-40		150 °C
Anzugsdrehmoment f. Modulmontage Mounting torque for modul mounting	Schraube M6 - Montage gem. gültiger Applikationsschrift Screw M6 - Mounting according to valid application note	M	4,25		5,75 Nm
Anzugsdrehmoment f. elektr. Anschlüsse Terminal connection torque	Schraube M4 - Montage gem. gültiger Applikationsschrift Screw M4 - Mounting according to valid application note	M	1,8	-	2,1 Nm
	Schraube M8 - Montage gem. gültiger Applikationsschrift Screw M8 - Mounting according to valid application note		8,0	-	10 Nm
Gewicht Weight		G		1200	g

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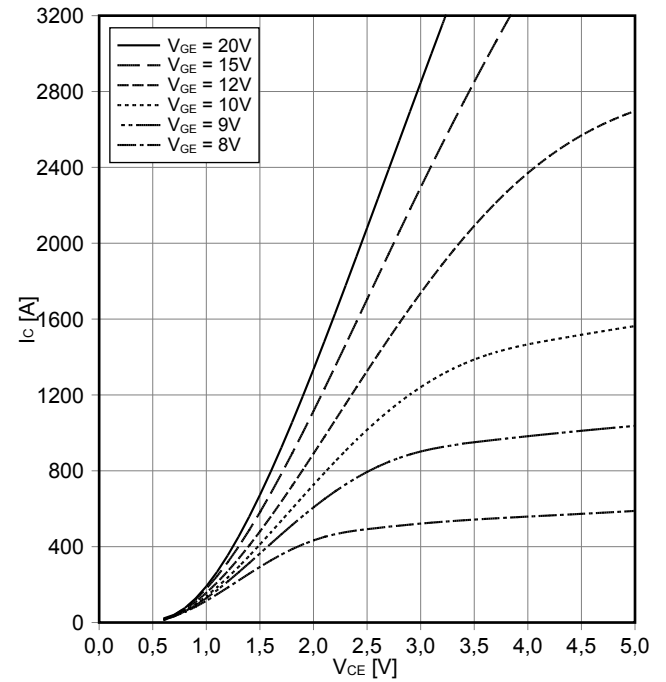
Ausgangskennlinie IGBT-Chopper (typisch)
output characteristic IGBT-Chopper (typical)

$I_C = f(V_{CE})$
 $V_{GE} = 15\text{ V}$



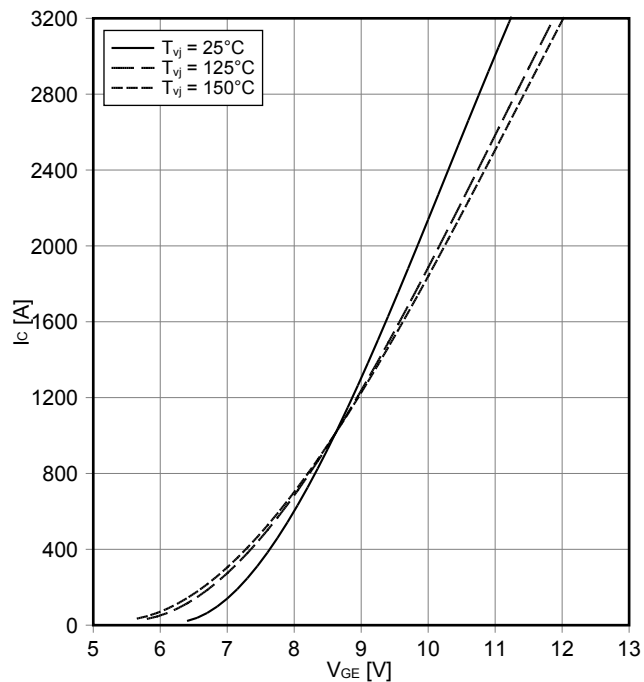
Ausgangskennlinienfeld IGBT-Chopper (typisch)
output characteristic IGBT-Chopper (typical)

$I_C = f(V_{CE})$
 $T_{vj} = 150^\circ\text{C}$



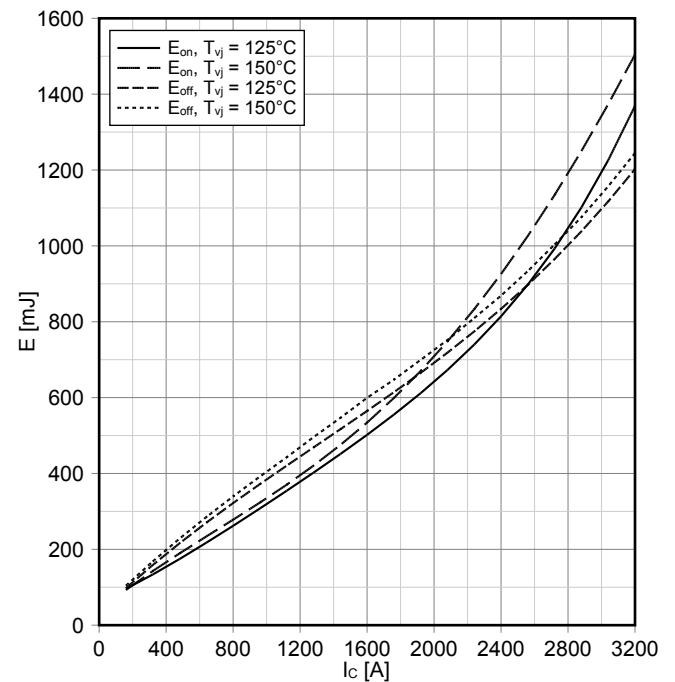
Übertragungscharakteristik IGBT-Chopper (typisch)
transfer characteristic IGBT-Chopper (typical)

$I_C = f(V_{GE})$
 $V_{CE} = 20\text{ V}$



Schaltverluste IGBT-Chopper (typisch)
switching losses IGBT-Chopper (typical)

$E_{on} = f(I_C)$, $E_{off} = f(I_C)$
 $V_{GE} = \pm 15\text{ V}$, $R_{Gon} = 1.1\ \Omega$, $R_{Goff} = 0.6\ \Omega$, $V_{CE} = 900\text{ V}$

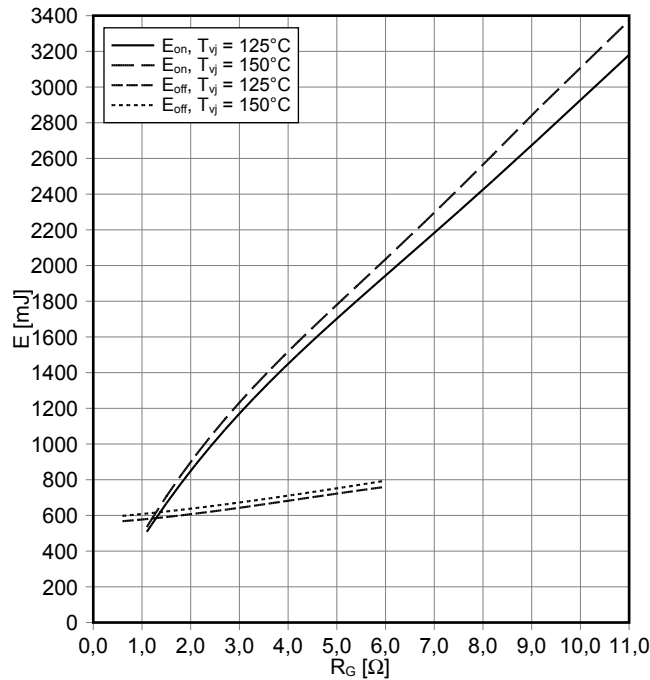


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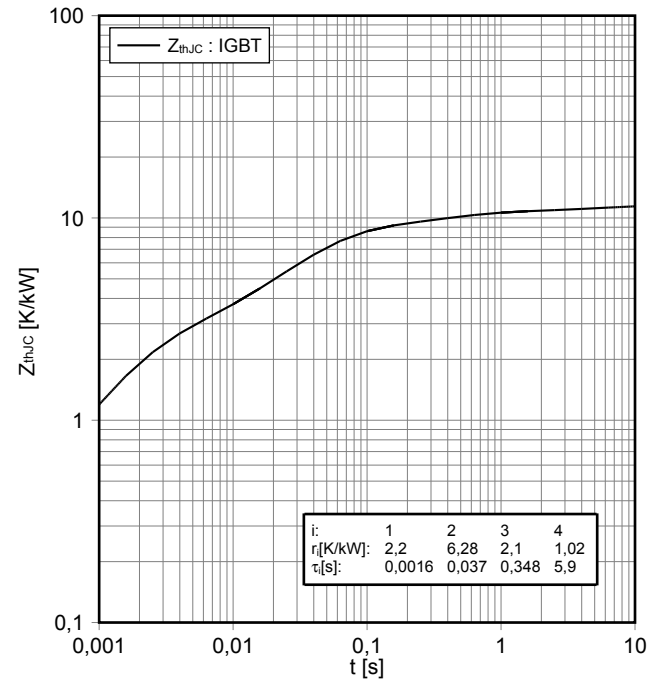
Schaltverluste IGBT-Chopper (typisch)
switching losses IGBT-Chopper (typical)

$E_{on} = f(R_G), E_{off} = f(R_G)$
 $V_{GE} = \pm 15 \text{ V}, I_C = 1600 \text{ A}, V_{CE} = 900 \text{ V}$



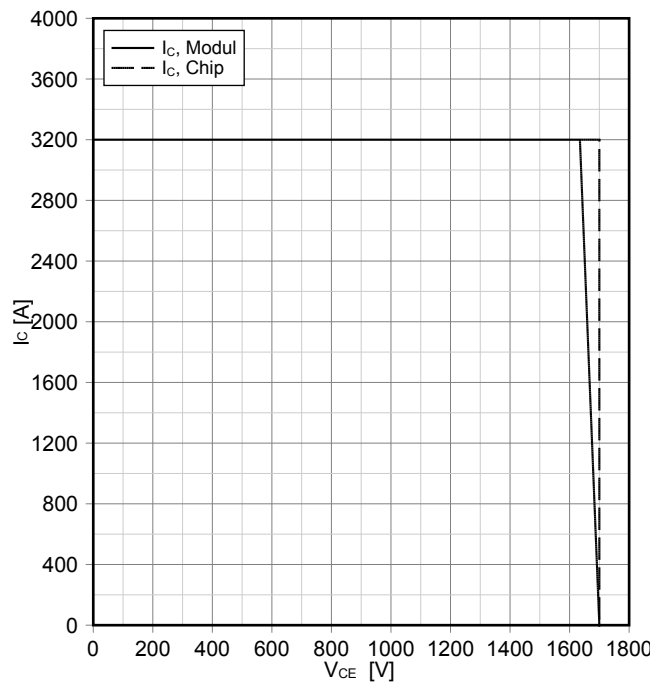
Transienter Wärmewiderstand IGBT-Chopper
transient thermal impedance IGBT-Chopper

$Z_{thJC} = f(t)$



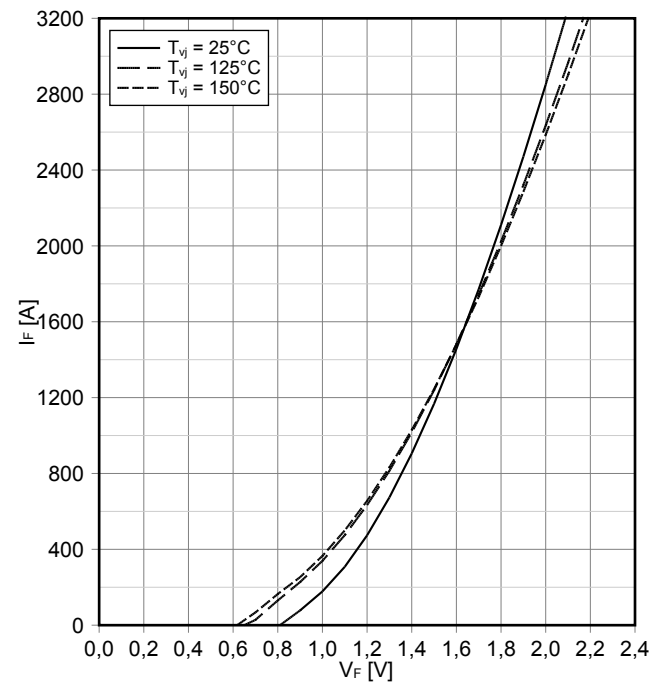
Sicherer Rückwärts-Arbeitsbereich IGBT-Chopper (RBSOA)
reverse bias safe operating area IGBT-Chopper (RBSOA)

$I_C = f(V_{CE})$
 $V_{GE} = \pm 15 \text{ V}, R_{Goff} = 0.6 \Omega, T_{vj} = 150^\circ\text{C}$



Durchlasskennlinie der Diode, Brems-Chopper (typisch)
forward characteristic of Diode, Brake-Chopper (typical)

$I_F = f(V_F)$

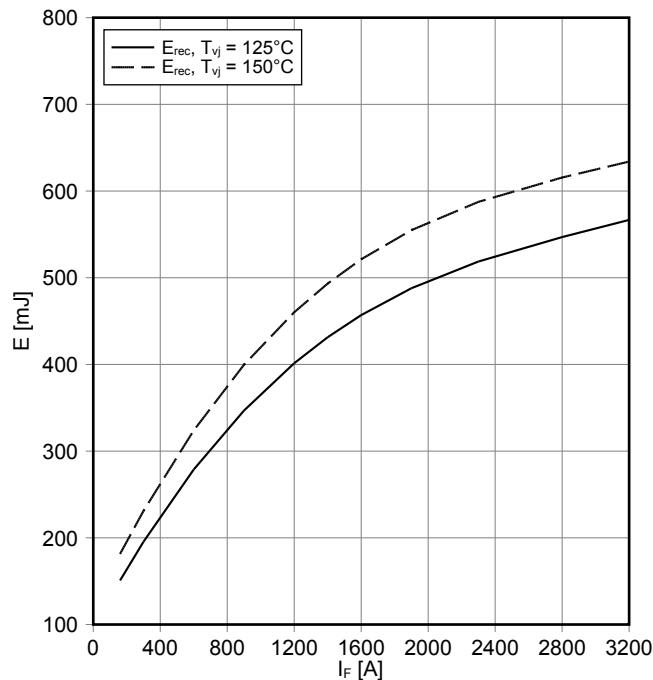


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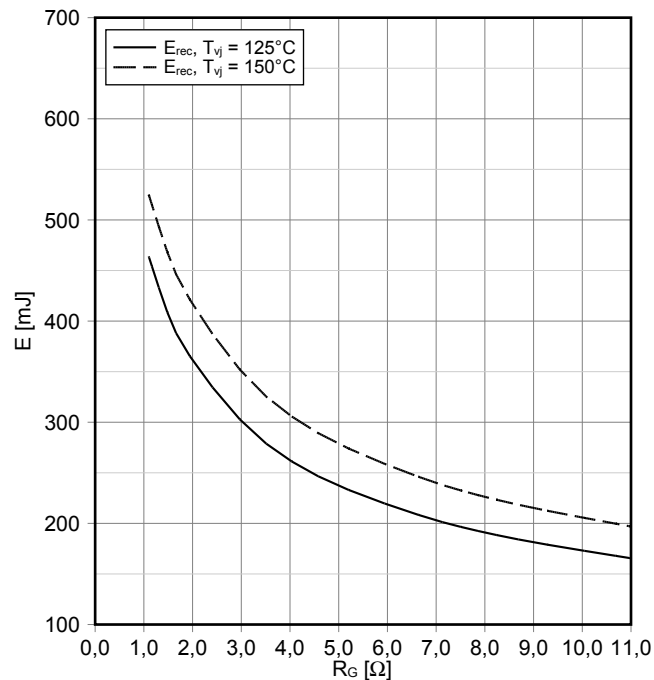
Schaltverluste Diode, Brems-Chopper (typisch)
switching losses Diode, Brake-Chopper (typical)

$E_{rec} = f(I_F)$
 $R_{Gon} = 1.1 \Omega, V_{CE} = 900 V$



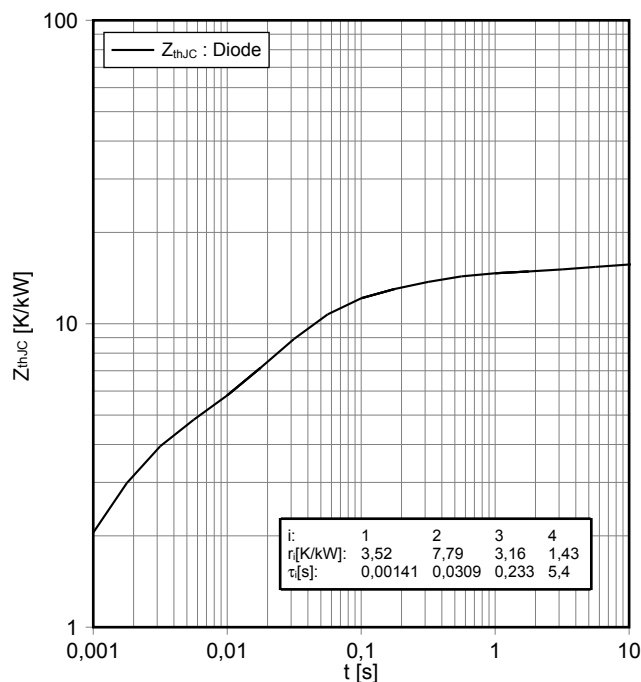
Schaltverluste Diode, Brems-Chopper (typisch)
switching losses Diode, Brake-Chopper (typical)

$E_{rec} = f(R_G)$
 $I_F = 1600 A, V_{CE} = 900 V$



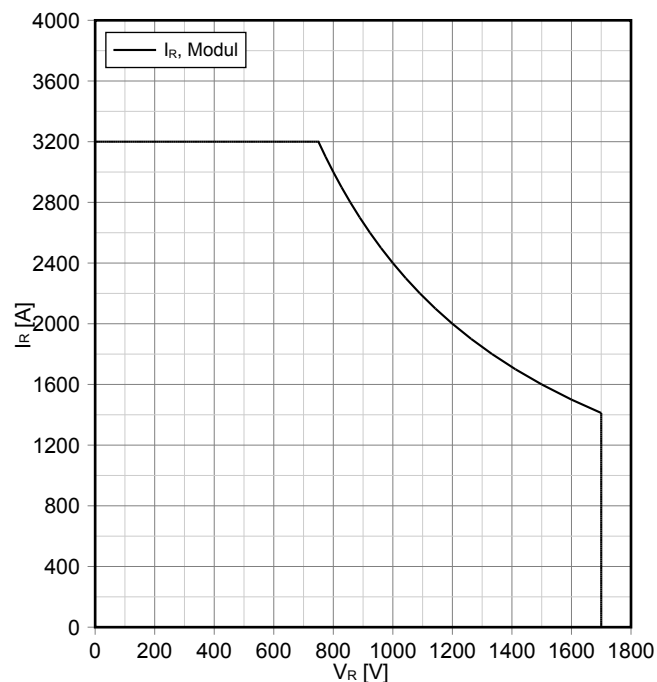
Transienter Wärmewiderstand Diode, Brems-Chopper
transient thermal impedance Diode, Brake-Chopper

$Z_{thJC} = f(t)$



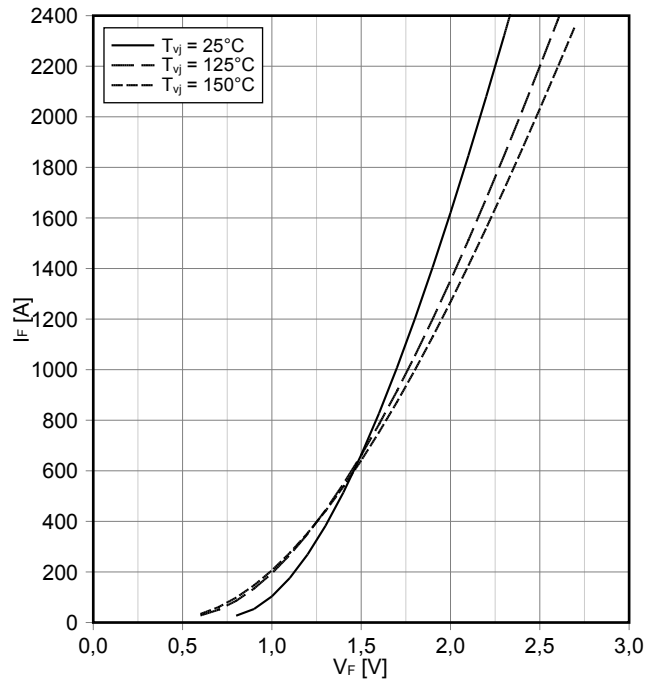
Sicherer Arbeitsbereich Diode, Brems-Chopper (SOA)
safe operation area Diode, Brake-Chopper (SOA)

$I_R = f(V_R)$
 $T_{vj} = 150^\circ C$

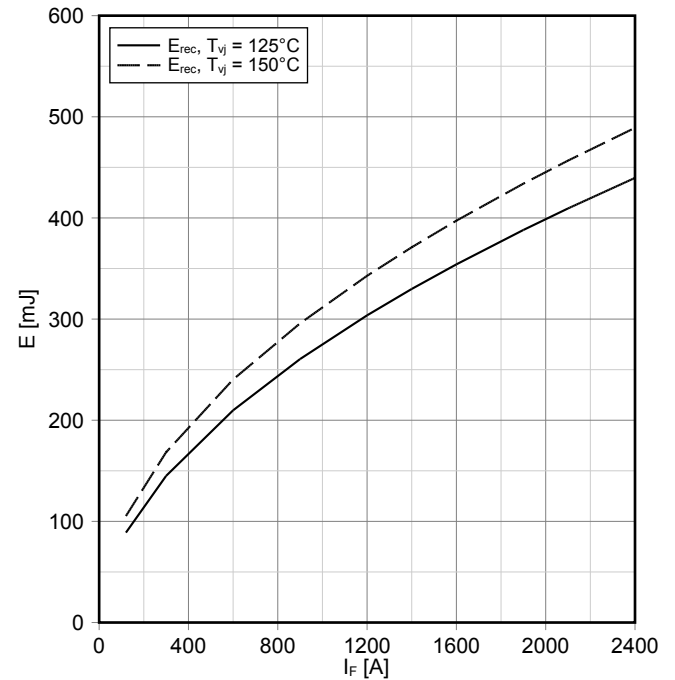


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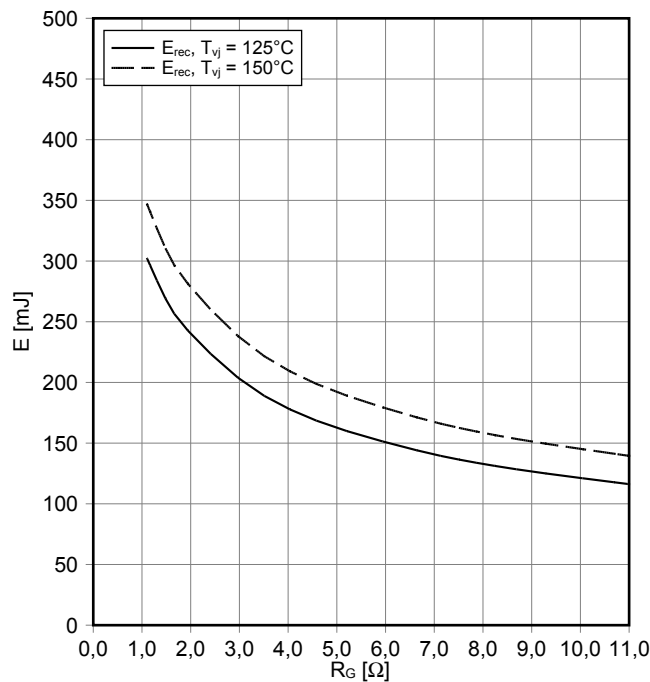
Durchlasskennlinie der Diode, Revers (typisch)
forward characteristic of Diode, Reverse (typical)
 $I_F = f(V_F)$



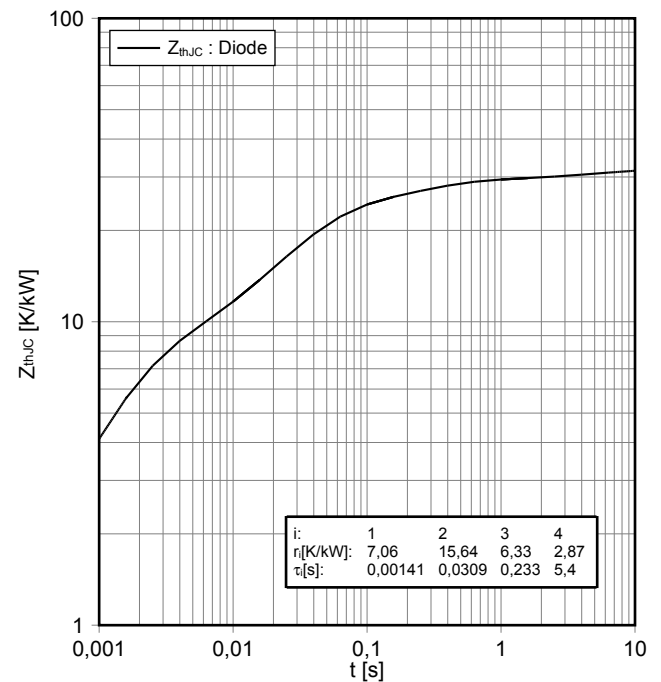
Schaltverluste Diode, Revers (typisch)
switching losses Diode, Reverse (typical)
 $E_{rec} = f(I_F)$
 $R_{Gon} = 1.1 \Omega, V_{CE} = 900 V$



Schaltverluste Diode, Revers (typisch)
switching losses Diode, Reverse (typical)
 $E_{rec} = f(R_G)$
 $I_F = 1200 A, V_{CE} = 900 V$



Transienter Wärmewiderstand Diode, Revers
transient thermal impedance Diode, Reverse
 $Z_{thJC} = f(t)$

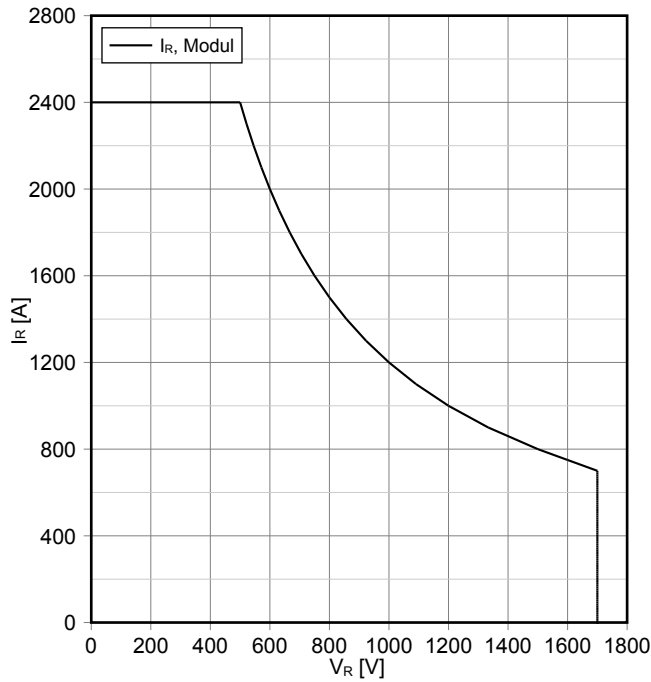


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Sicherer Arbeitsbereich Diode, Revers (SOA)
safe operation area Diode, Reverse (SOA)

$I_R = f(V_R)$
 $T_{vj} = 150^\circ\text{C}$



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